

# AM Part Qualification by ICME Analysis and Real Time NDE Monitoring (*Additive Manufacturing Science*)

Frank Abdi<sup>1</sup>, Rashid Miraj<sup>1</sup>, Clement Tam<sup>1</sup>, Isis Roche Rios<sup>2</sup>, Vasyli Harik<sup>1</sup>

<sup>1</sup>AlphaSTAR Corporation, Long Beach, CA, USA

<sup>2</sup>Raytheon Missile System, Tucson, AZ, USA

March 30, 2020

# Technical Agenda

## 1. Motivation/Problem

## 2. Micro Structure Material Modeling

- **Gain Modeling (Diffusional Creep):** Defects, Cracks, Oxidation, Surface Roughness
- **Mechanical Properties Prediction:** Stress-Strain Curve, Effect of Voids
- **Fracture –Fatigue Properties Prediction:** Toughness, Fatigue Crack Growth

## 3. Process Model

- **Path Coverage:** Defects
- Residual Stress, Net Shape, shrinkage
- Topology Optimization/DOE

## 4. Thermal Management:

- **Thermal State:** Heat Affected Zone, Melt, Super melt, Super heated Cool, Sintering/Consolidation, Cooling
- **Material state:** (density, void), and
- Process Map (Power, Velocity, Temperature)

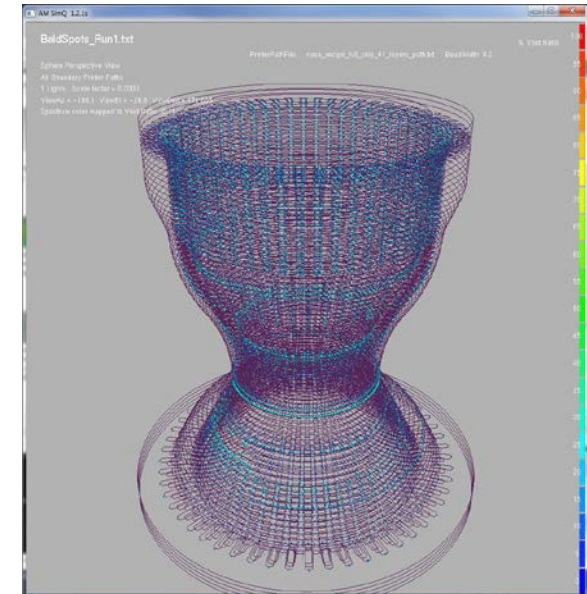
## 5. Qualification & Quality Assurance:

- a) **AM Properties:** Scatter uncertainties
- b) **Service Loading:** Static, Fracture control Plan, Fatigue, Life

## 6. Emerging Technology: In-Situ Monitoring

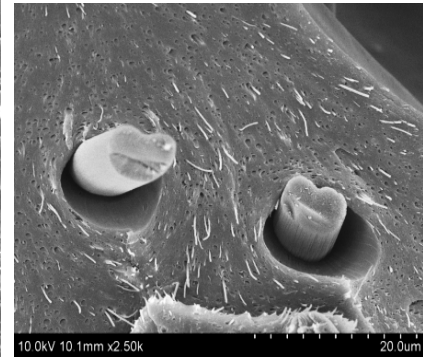
## 7. Conclusion

### Void Detection Chamber Nozzle (Inconel-718)

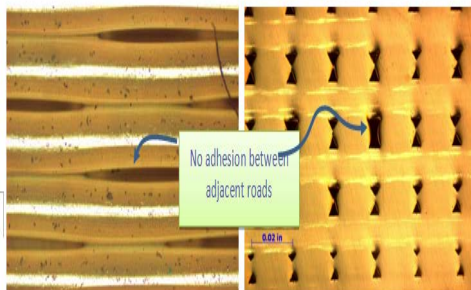


# Key Challenges: to Polymer Additive/Reactive Manufacturing

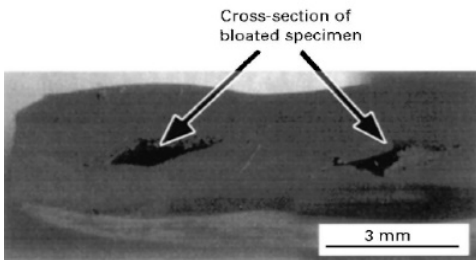
*A large number of variables can influence the number and locations of defects in the additively manufactured part.*



Weak Fiber-Matrix Interphase



Delamination & Porosity



Reactive: Bloating & Acid Formation

- Shrinkage and Warpage
- Cracks and Delamination
- High Porosity
- Interfacial Bonding
- Residual stress
- Wrinkles
- Fiber Waviness and Agglomeration
- Others

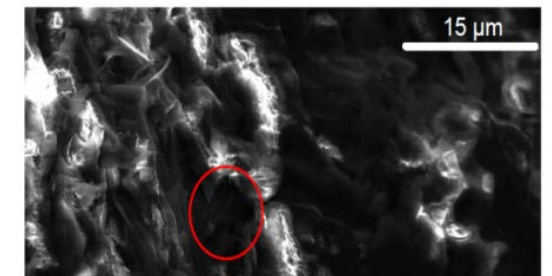


Cracks within/between Beads

*These challenges can be addressed using ICME material modeling and print error management tool sets*



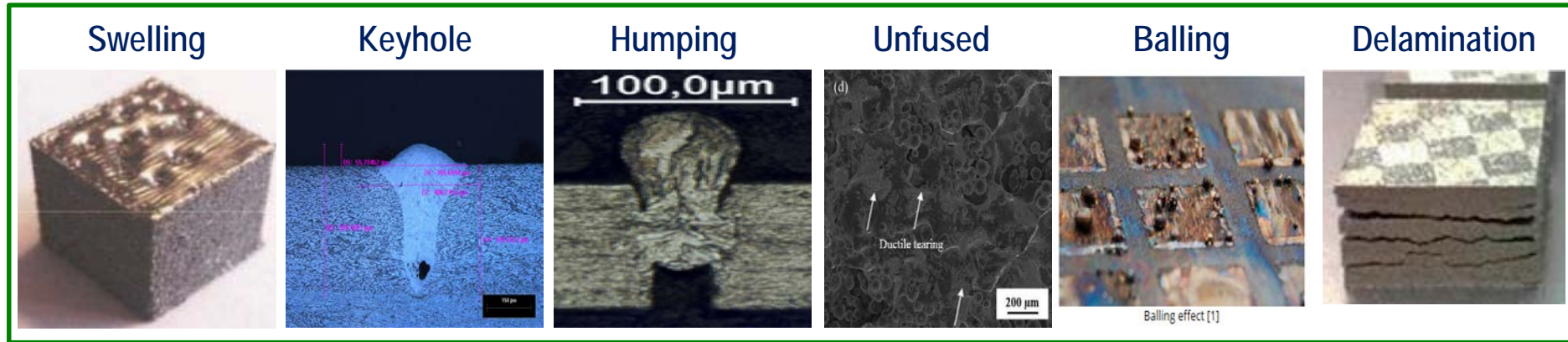
Delamination



Wrinkle in Thermoset:  
due to residual stress, interphase,  
surface functionalization

# Challenges in Metal AM

## Defects Resulting From AM Process Related to Thermal Behavior



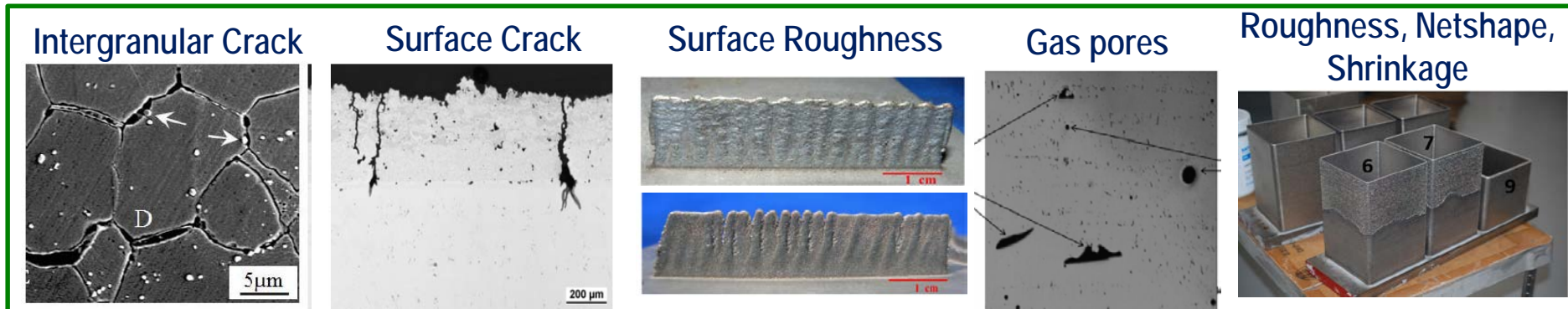
### When It Happens?

- High Residual Stresses
- Surface Roughness
- Voids and Cracks
- Oxidation
- Inconsistent Density
- Anisotropic Microstructure
- Mechanical Behavior

### Consequences?

### Why It Happens?

- Speed and Power Range (All Phenomena)
- Unfused Powder: Insufficient Melting
- Humping: Meltpool Length and Duration
- Humping: Meltpool Pile-up
- Gas Pores/Keyhole: Trapped Gas in Particles
- Swelling & Balling: Surface Tension Effects



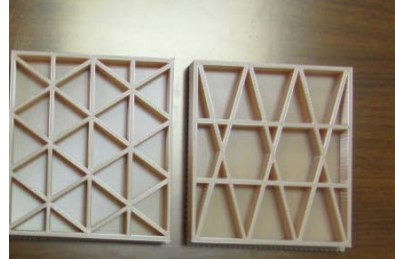
# GENOA3DP – ADDRESSES METALS, POLYMERS, AND CERAMICS

Composite

3D Printed Shelby Car  
Minimize Delamination



Multi Material (ULTEM-Silver)  
Diffusion/Inclusion



Wing (Thermoplastic-PPS)  
Delamination/CTE



Ceramic Part (Binder Jet)  
PIP & Voids

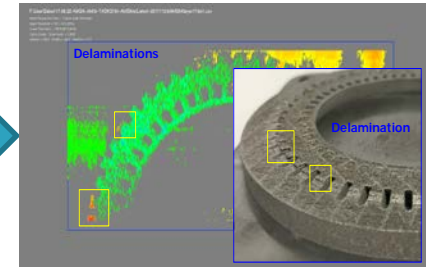


Metal

UAV Wing (Titanium)  
Design Stress Free Support Structure



Heated Chamber Nozzle (Inconel)  
In-Situ Roughness



Box (Inconel)  
Roughness & Net Shape



Conformal HeX (steel)  
Weight Minimization, Thickness & Leakage



Mount Ring (Inconel 718)  
Roughness, Warpage, Base Plate & Support Design



# In-Situ Monitoring

*Benefit of Big Data Processing/Discovery: Monitor Defects in Real Time*

- Big Data Monitoring, Real-time Process
- **Visualization**
  - Surface Roughness by Profilometer
  - Heat Affected Zone from IR Thermal Camera
  - Photo-Diodes: Melt pool, Plasma duration
- **Calculation**
  - Real-Time Calculation
    - Heating, Melt pool, Solidification, Cooling
  - Absorption of Laser Energy in Powder
  - Microstructure and Voids

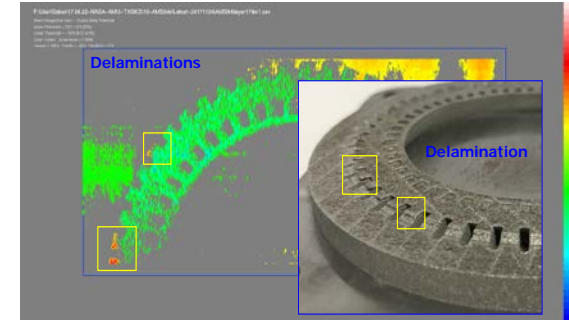


Profilometer/IR Camera



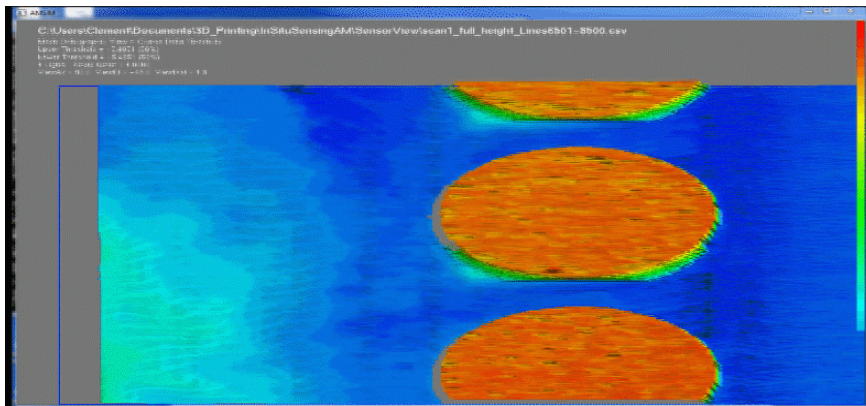
IN718 Chamber Liner

Roughness/Delamination

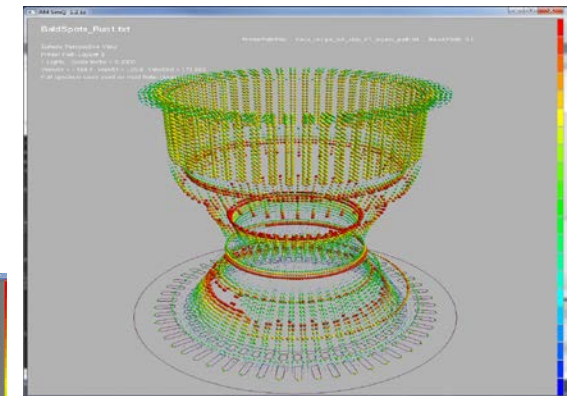
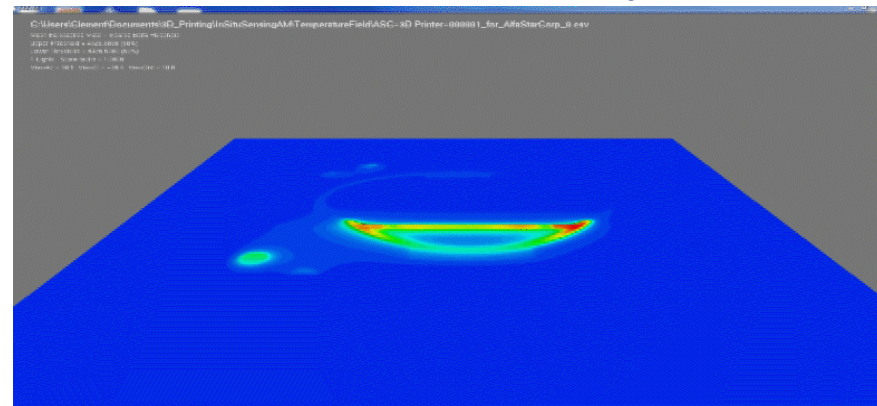


3D Visualization Anomaly Size/Intensity

Surface Roughness from Laser Profilometer



Heat Affected Zone Processing (IR)



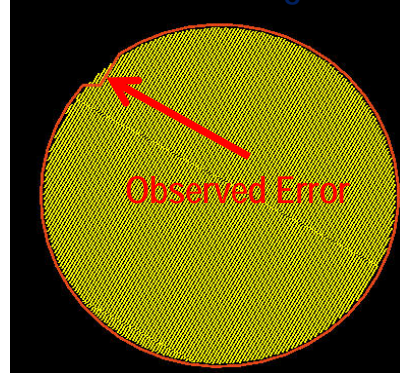
# In-Situ Monitoring: Surface Roughness and Thermal Map

*Real-Time Big Data Processing: Printing Error, Thermal Map, Roughness Visualization/Processing (Profilometer & Thermal Data)*

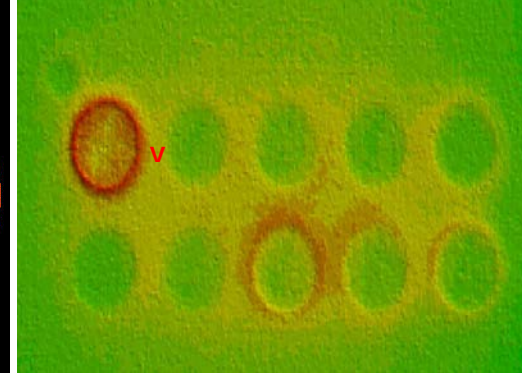
10 Inconel-718 Coins Printed  
Different Power & Speed



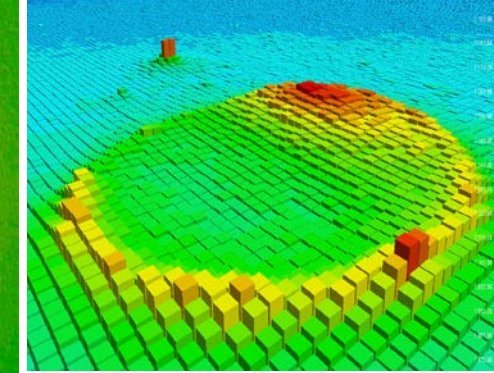
Detected Printing Errors by  
PathCoverage



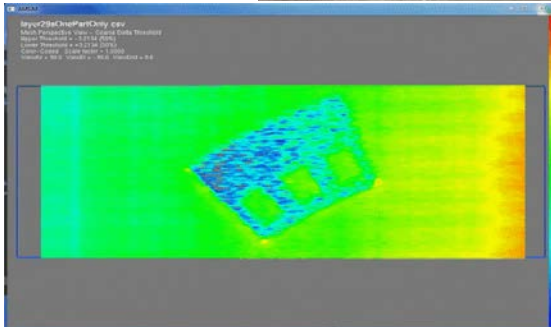
Single Layer Thermal



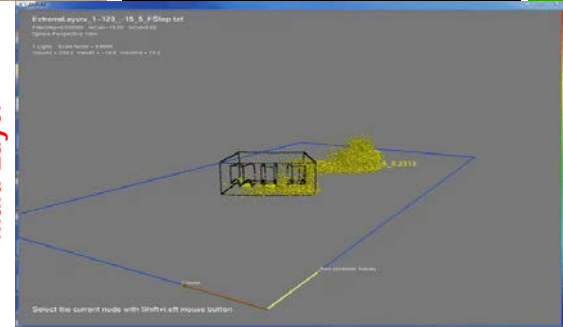
Material: Inconel-718  
Observed Splatter



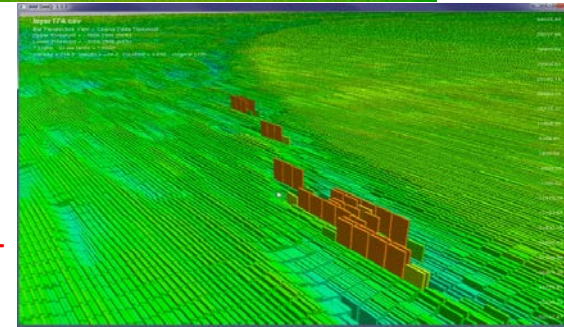
Single Layer



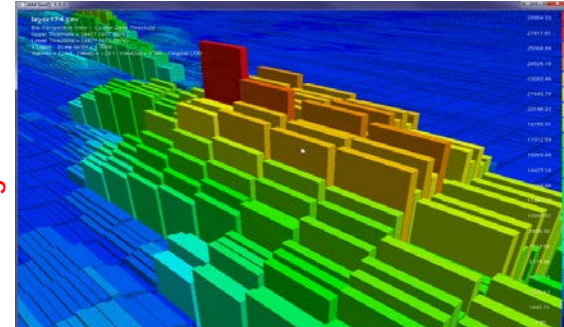
Multi Layer



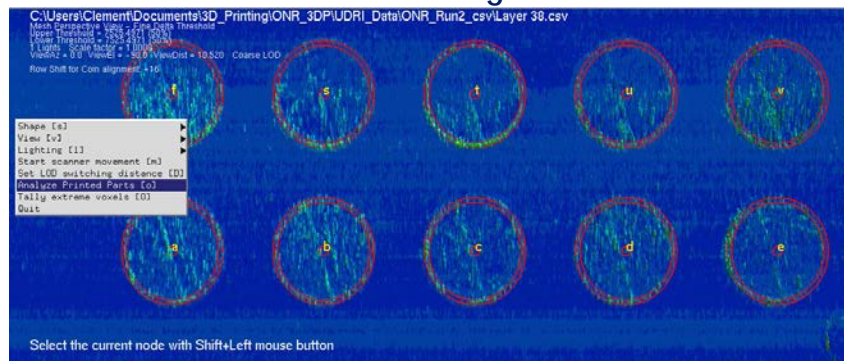
Super Elevation



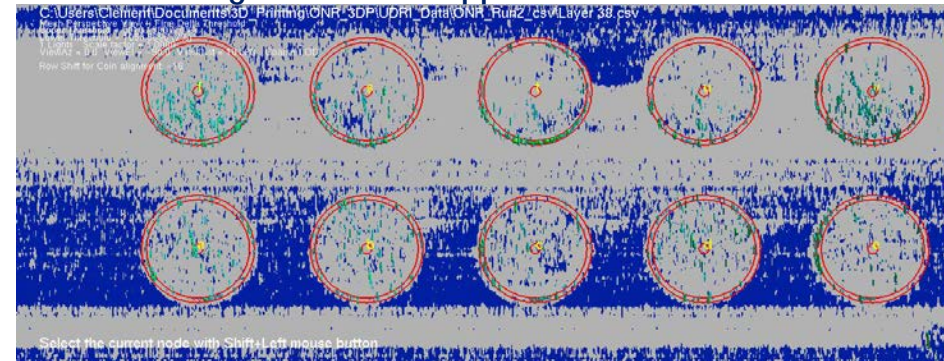
Roughness



Unfiltered voxels for Roughness Calculation



Roughness Filters applied for Voxel Tallies



# Part Qualification Account for Defects

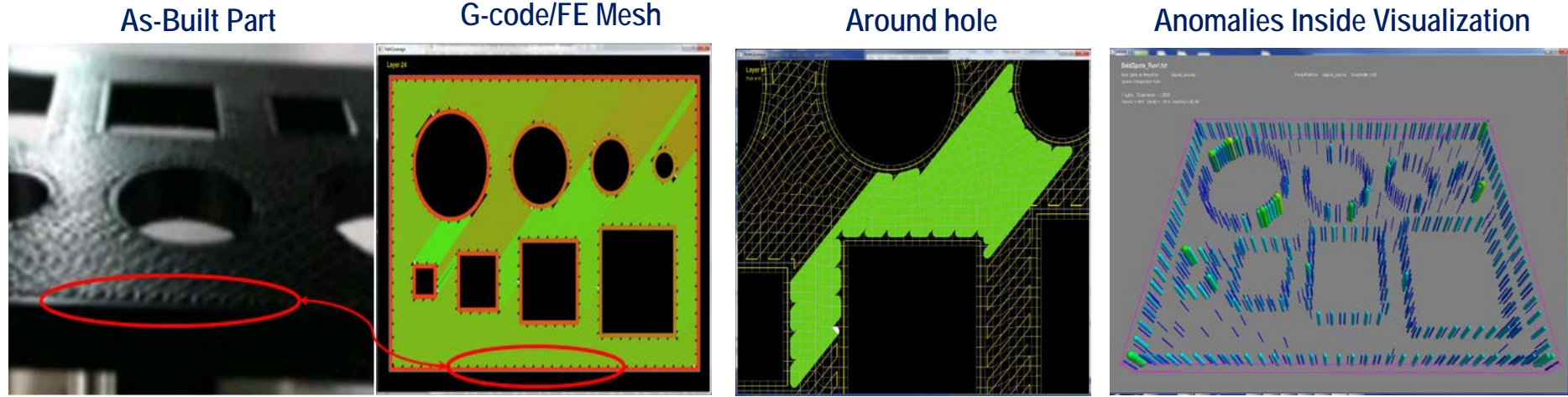
## *GENOA 3DP PathCoverage: Anomalies Visualization, Material Degradation*

PathCoverage: Tracks Void (shape, size, distribution), Predicts Stiffness/strength Degradation

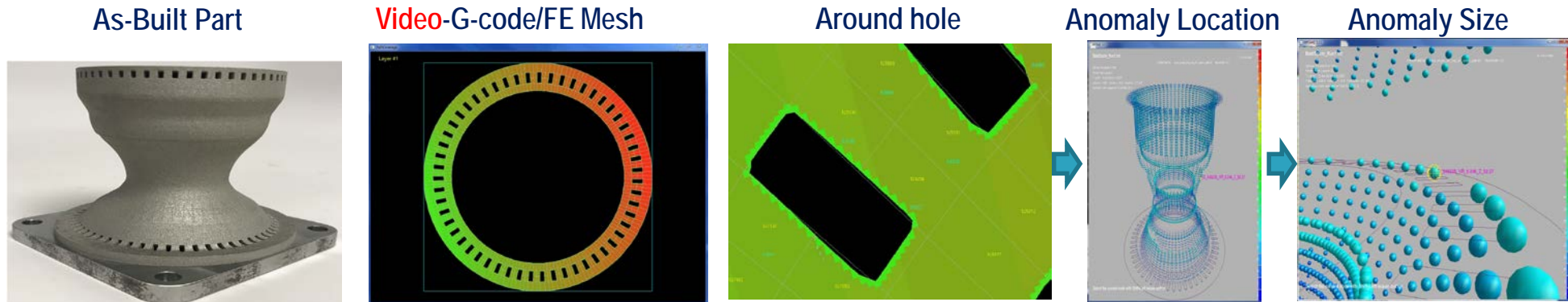
Methodology: Inputs: bead width, gcode, FE mesh

— Superimpose G-code to FE mesh calculating material properties (strength/stiffness) degradation per element

### Polymer



### Metal Powder





# GENOA 3DP Thermal Management (TMg) -Micro Scale

## E. Process map

**A. Extremely fast calculation and high accuracy**

**B. Predicts Thermal History (6 regions)**

i) Heating, ii) Melting, iii) Melt-superheated iv) Superheat-cooling v) Solidification/Sintering & vi) Cooling

**C. Calculates Meltpool size/shape**

Length, Width, & Depth

**D. Calculates transient material states** Density, Volume of Solid (VOS), void ratios

**E. Predicts 3D dynamic process map** (power, speed, vs. temperature)

safe/unsafe regions & optimum printing parameters to avoid defects due to Thermal behavior

**F. Grain-boundary engineering (Beta-Release)**

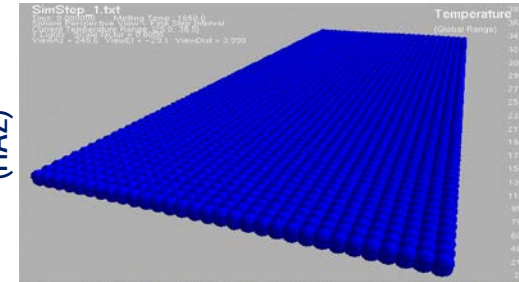
Phase-Diagram, Crystallization, Temperature Time Transformation (TTT) Diagram, Continuous Cooling Transformation (CCT), Fine/Coarse Grains

**Data Base:**

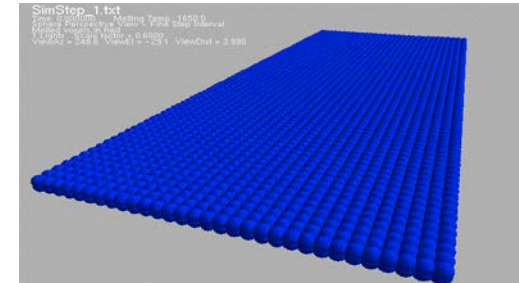
**Metal:** Titanium, Steel(SS 316L), Inconel 718, AISi10Mg

**Polymer:** PA11, PA12, ABS (CF), ULTEM (9085, 1010), PLA

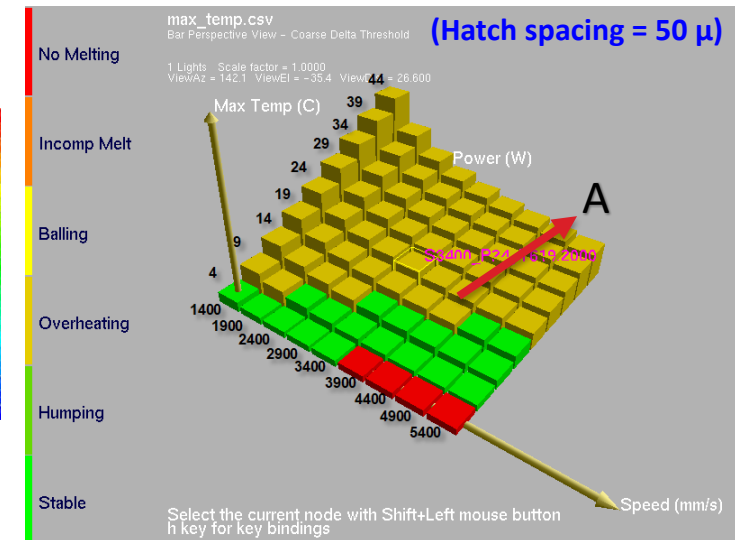
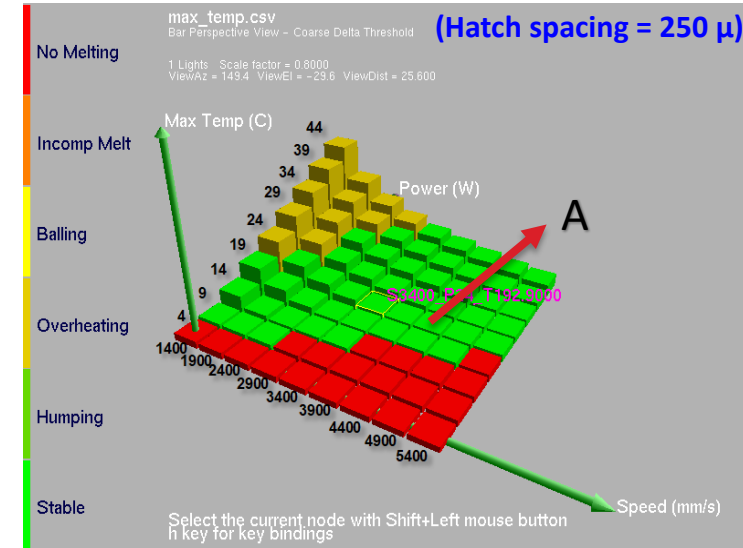
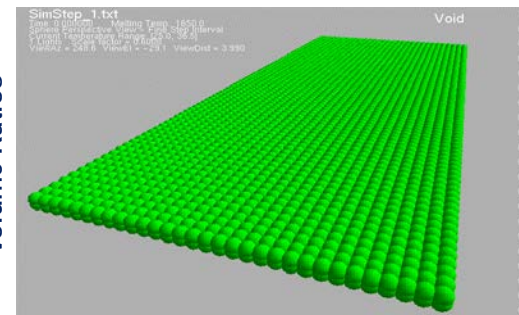
B. Thermal History (HAZ)



C. Dynamic Meltpool



D. Transient Void Volume Ratios

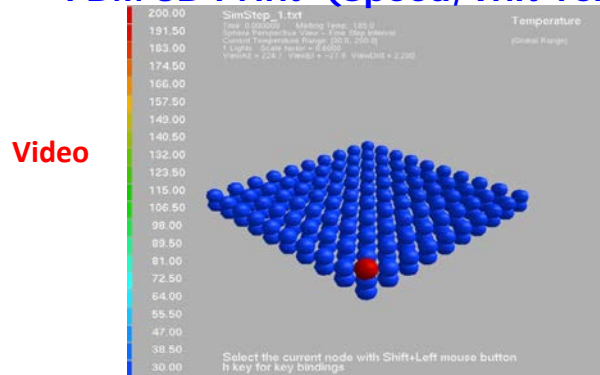


# Microscale Thermal Management (TMg): FDM Vs. SLS

## Prediction/Comparison of Meltpool, Density, Voids & VOS in FDM and SLS

FDM 3D Print (Speed, Init Temp)

SLS 3D Print (Power, Speed)

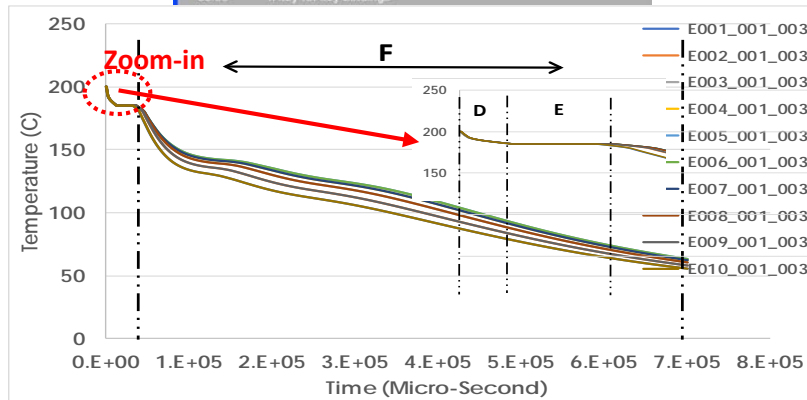


Video

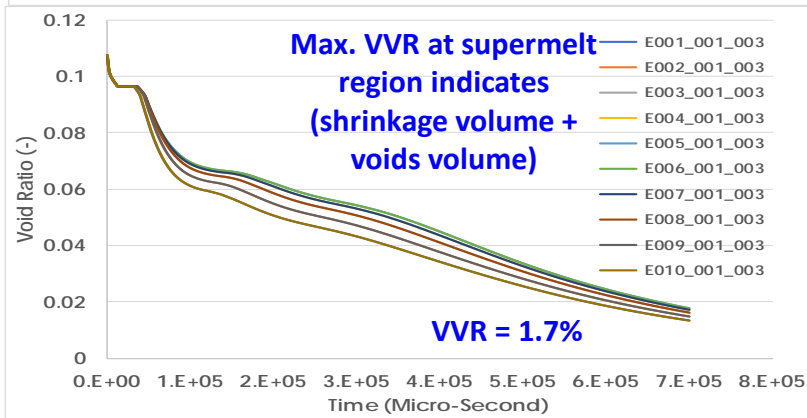
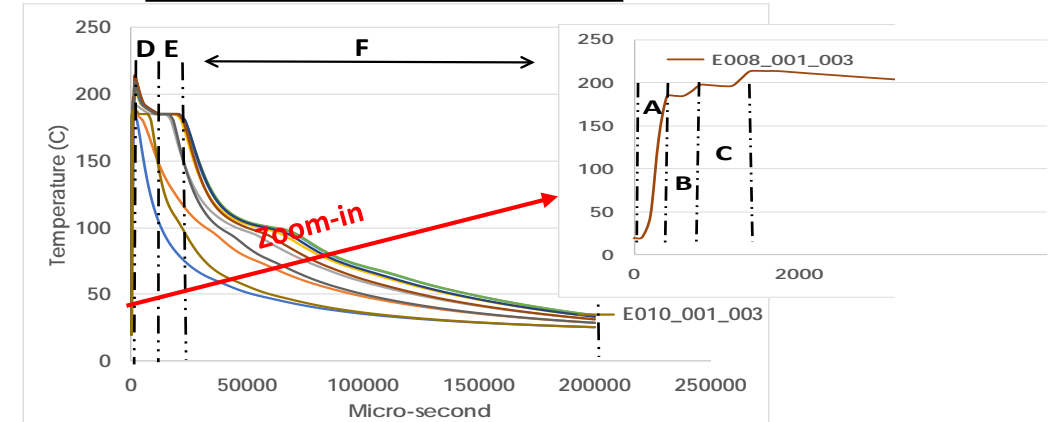
- A: Heating
- B: Melting
- C: Melt-Supermelt
- D: Superheat-Cooling
- E: Solidification
- F: Cooling



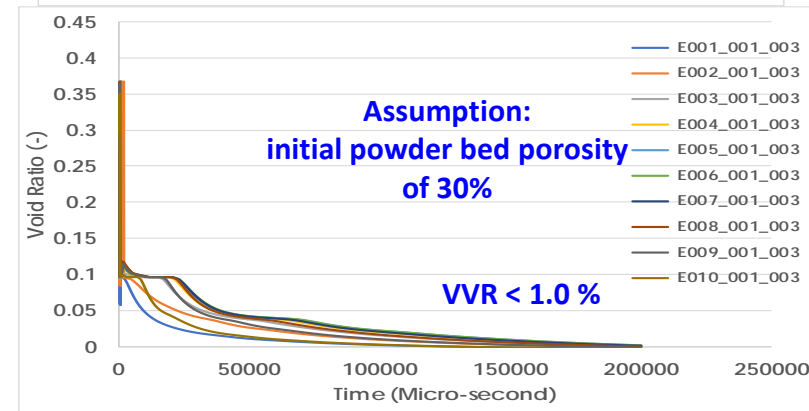
Video



Temperature (°C) vs. Time (μs)



Void (-) vs. Time (μs)

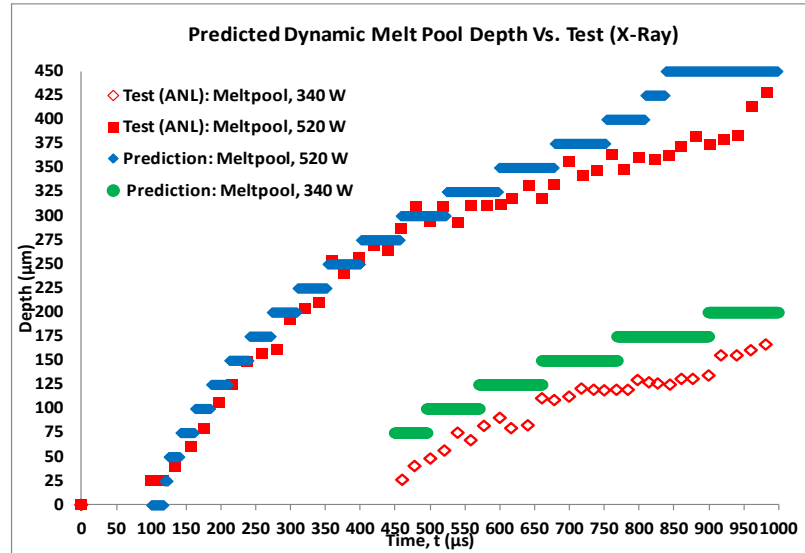


# Case Study: Validated Dynamic Meltpool Evolution

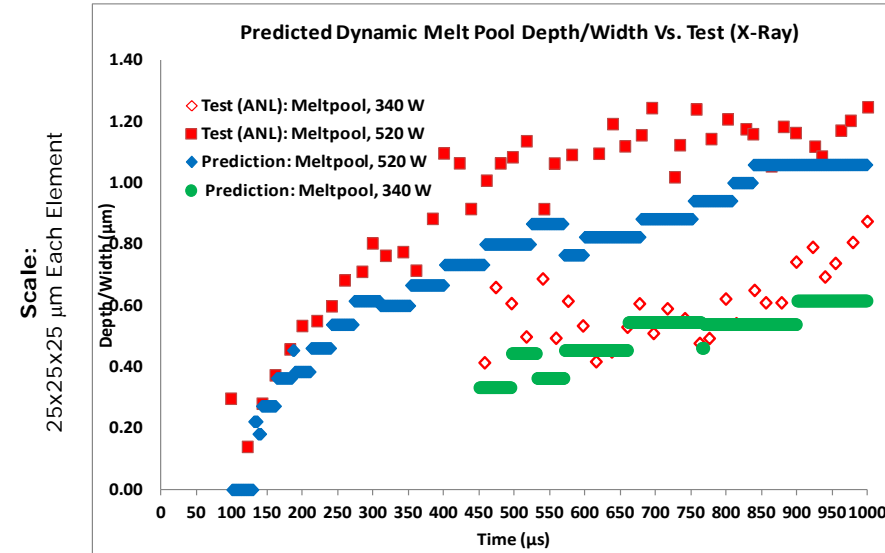
## Validated Dynamic Meltpool Depth & Width (Micro-scale): TMg vs. X-ray Image

Material: Ti-6Al-4V

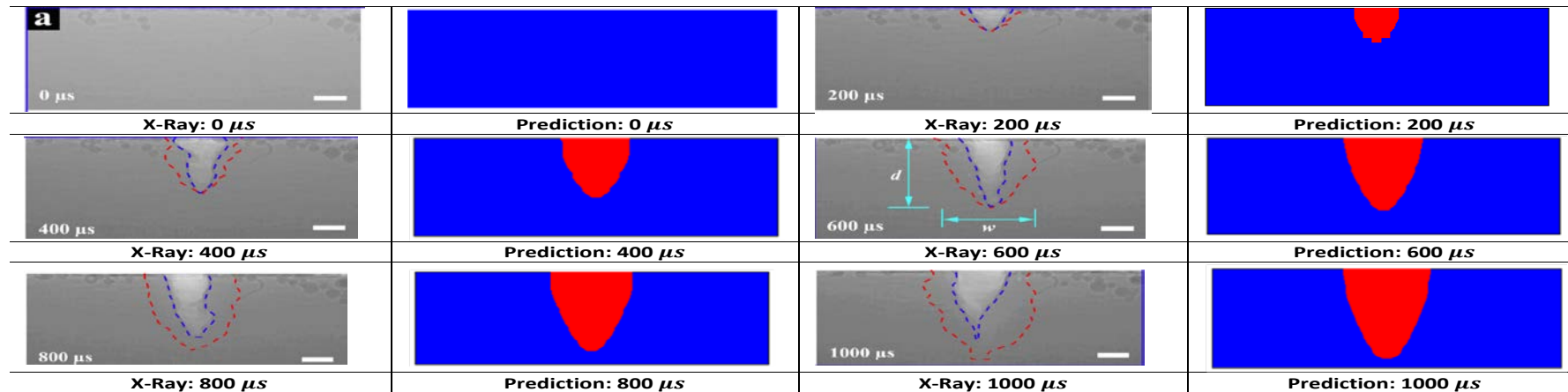
Meltpool Depth vs. Time: 3DP TMg VS. X-Ray



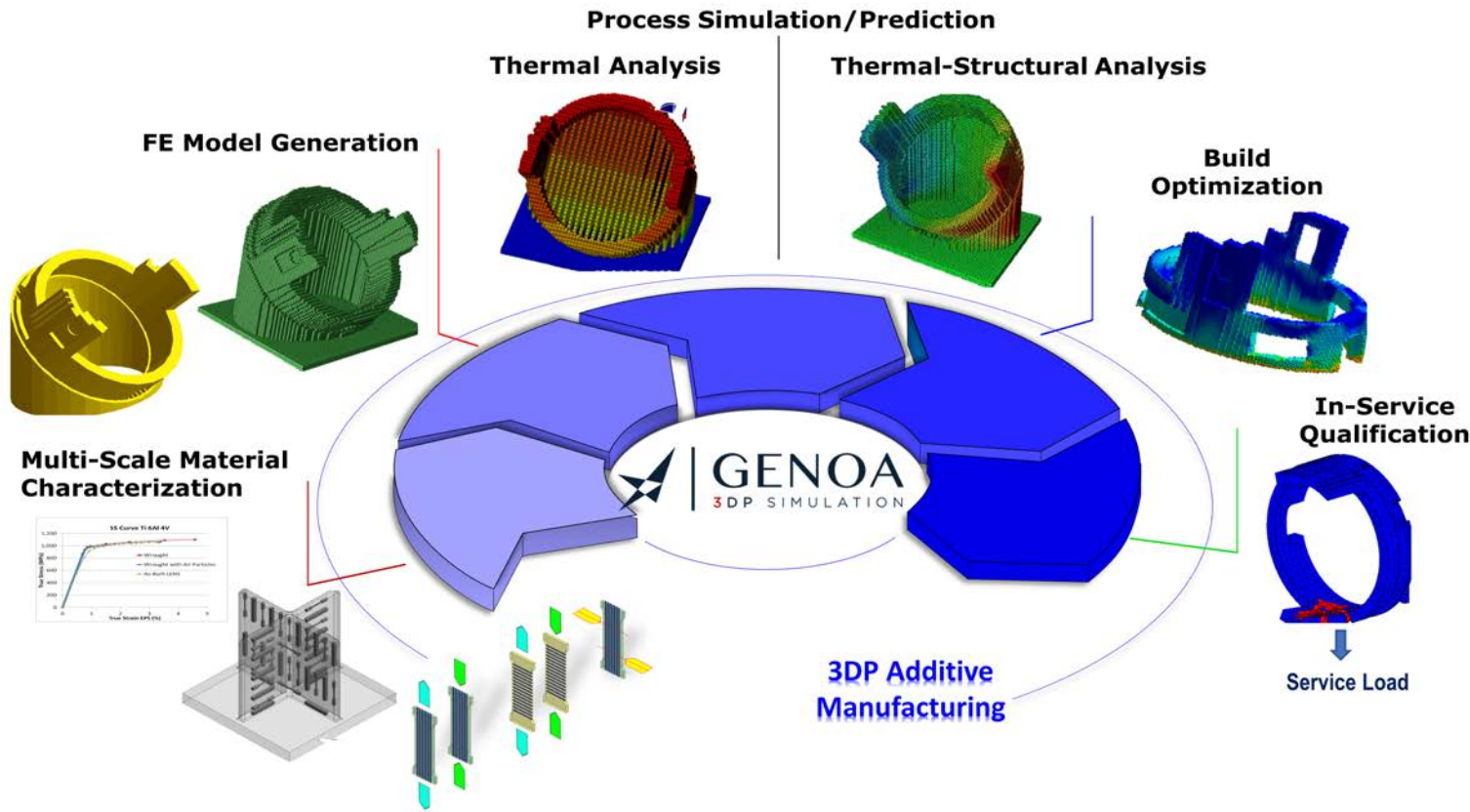
Meltpool Depth/Width vs. Time: 3DP TMg VS. X-Ray



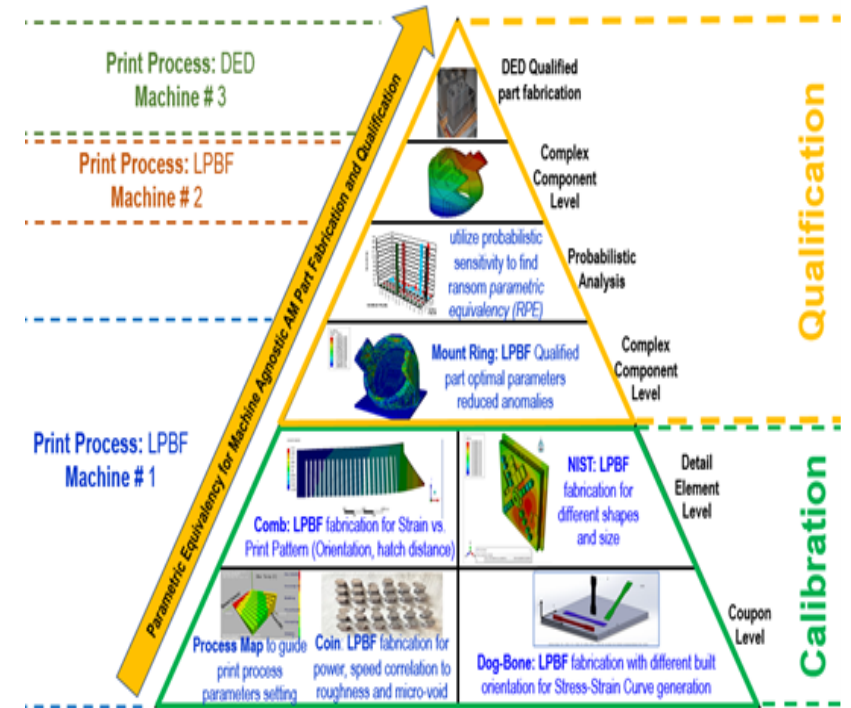
Validated Dynamic Meltpool Evolution, Power = 520 W, 3DP TMg VS. X-ray Image, Laser Powder Bed Fusion (LPBF)



# ICME Workflow for Metal AM



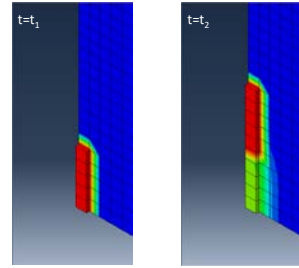
## Building Block Validation



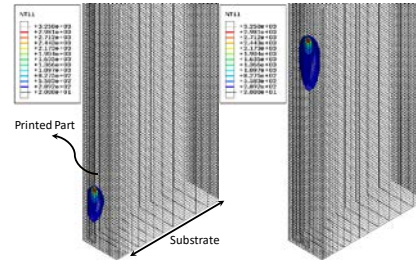
# AlphaSTAR Metal ICME Tool

## Multi-Scale Modeling: Material, Process, Qualification

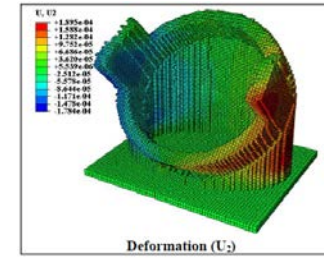
Process/  
Qualification



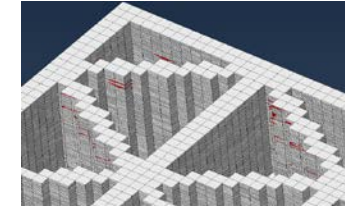
Heat Affected Zone



Melt Pool Prediction



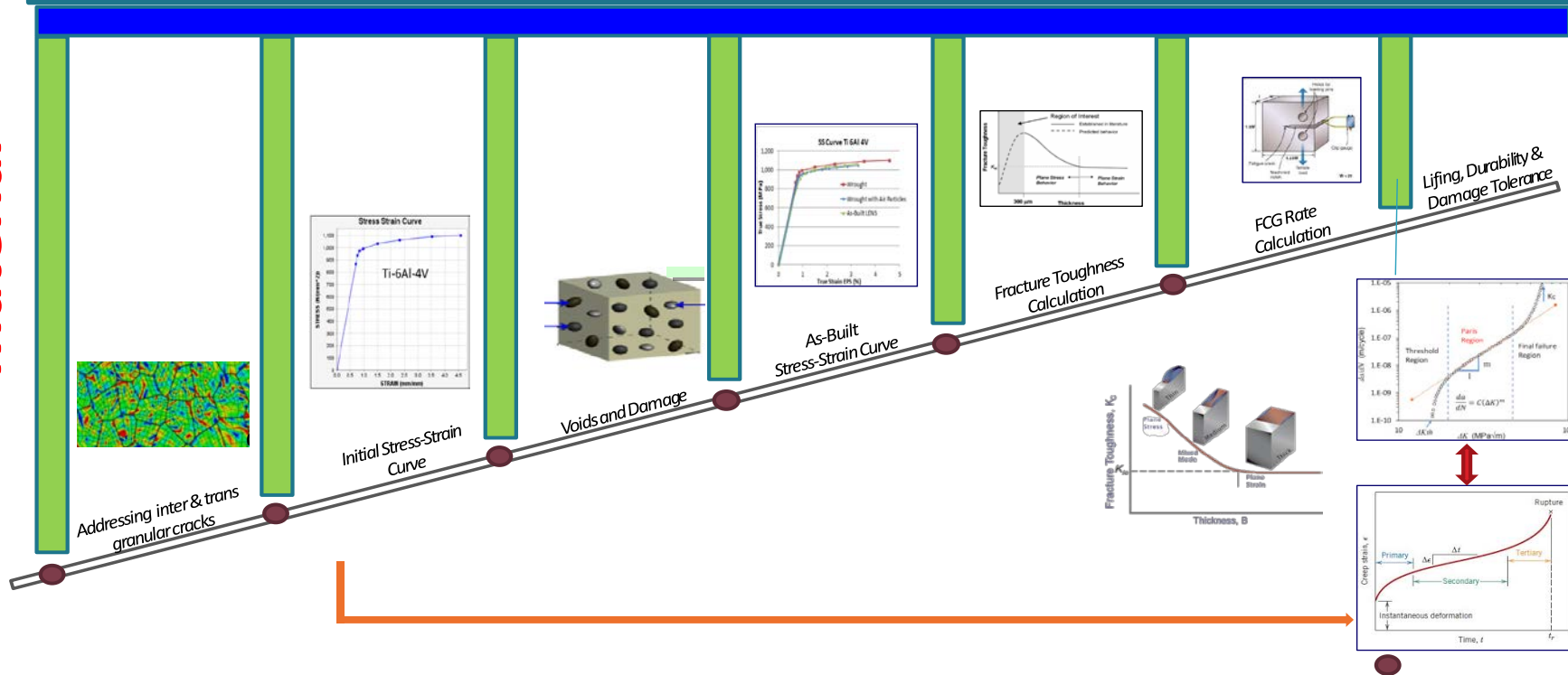
Net Shape



Damages

Material

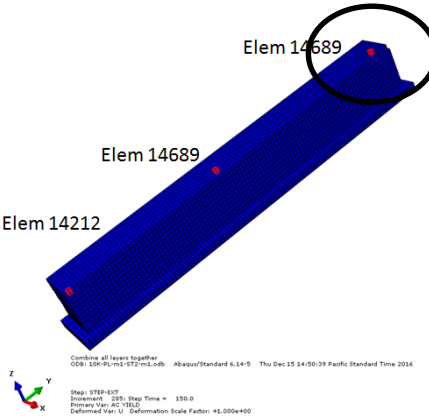
### Micro-Scale - Continuum



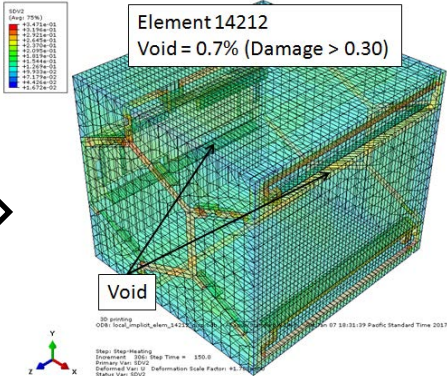
# Global Local Modeling

Diffusional Creep: Predict Void, Oxidation, Residual Stress in local model

## Global Model



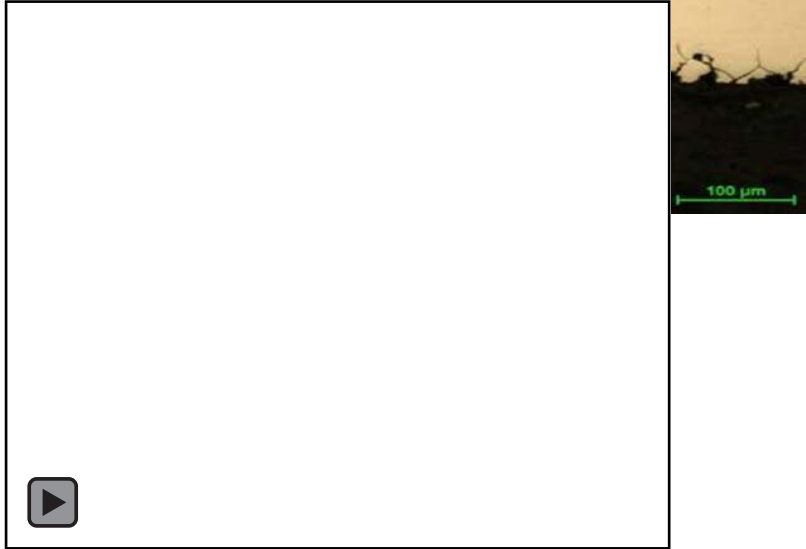
## Void



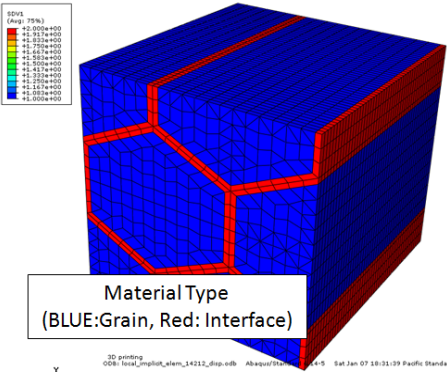
## Oxidation/Diffusional Creep Video



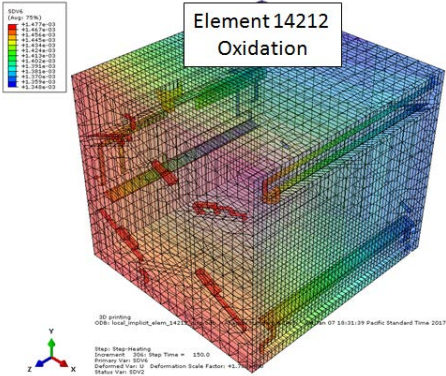
## Oxidation creep



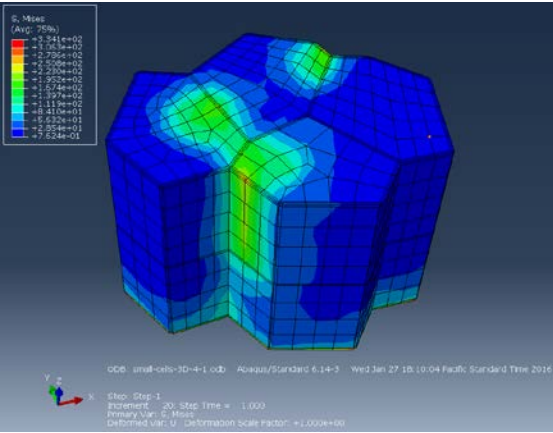
## 3D Local Model



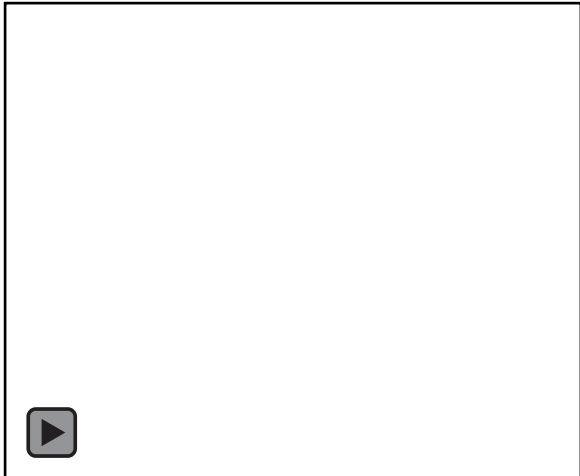
## Oxidation



## Residual Stress



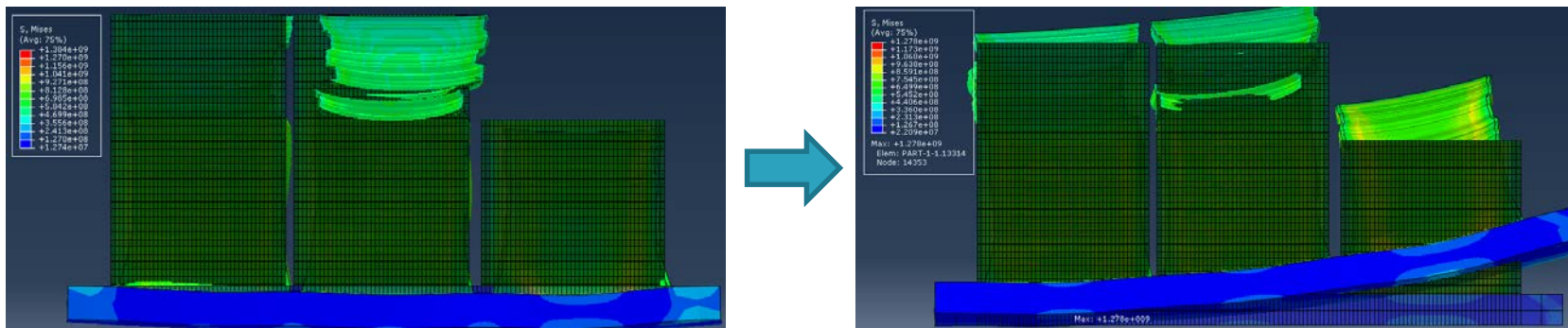
## 130 MPa Von Mises stresses



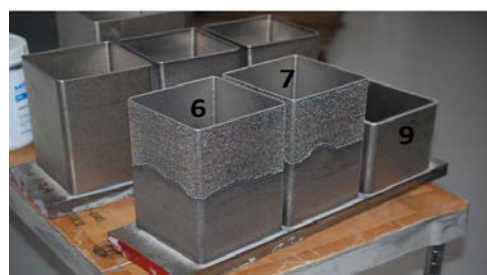
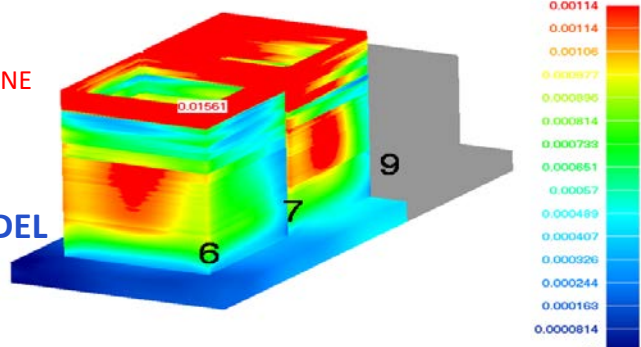
# Part Qualification

## Net Shape: Sensitivity to Bolt (Fixed Corner) Removal

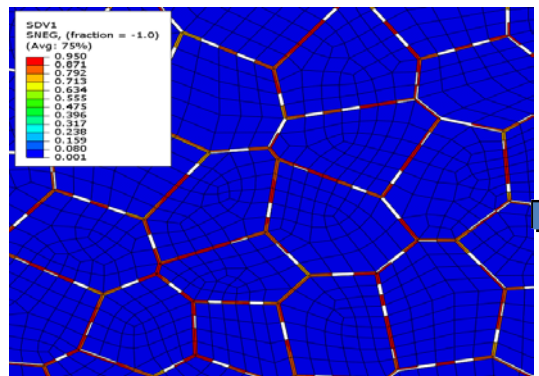
Redistribution of Residual Stress While Removing Clamps



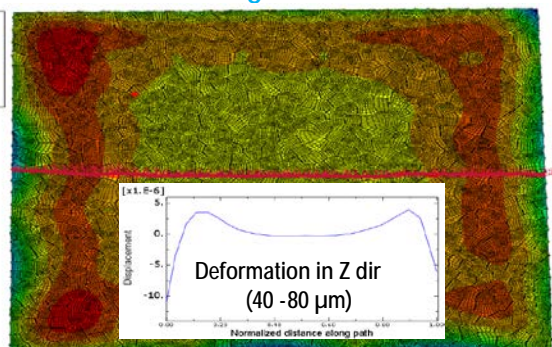
RED = SURFACE ROUGHNESS ZONE



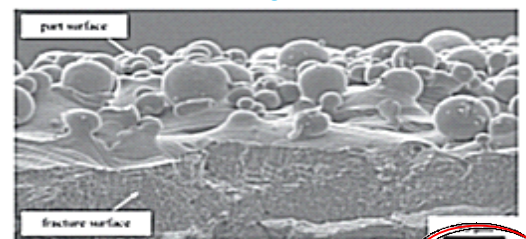
GLOBAL-LOCAL MODEL



Predicted Surface Roughness



Measured Surface Roughness



50 Micron

# 3D Printing SS Curve Prediction vs. Test

*DMLS Material Model, Nano Based Inclusion/Defects Algorithm*

## Input Properties for Ti-6Al-4V and Inclusion

**Ti-6Al-4V**

- Description: Ti-6Al-4V
- General
  - Density:  $RHO = 2.800000E-09 \text{ tonne}/(\text{mm}^3)$
- Mechanical
  - Modulus:  $E = 1.240000E+03 \text{ N}/(\text{mm}^2)$
  - Poisson Ratio:  $\nu = 3.300000E-01$
  - Strength
    - ST =  $1.100000E+03 \text{ N}/(\text{mm}^2)$
    - SC =  $1.100000E+03 \text{ N}/(\text{mm}^2)$
    - SS =  $8.250000E+02 \text{ N}/(\text{mm}^2)$

**Air as Inclusion**

- Particle
  - Description: Air-Particles
  - Type: Isotropic
  - General
    - Density:  $RHO = 1.295000E-12 \text{ tonne}/(\text{mm}^3)$
  - Mechanical
    - Modulus:  $E = 1.000000E+00 \text{ N}/(\text{mm}^2)$
    - Strength
      - ST =  $1.000000E+00 \text{ N}/(\text{mm}^2)$
      - SC =  $1.000000E+00 \text{ N}/(\text{mm}^2)$
  - Interface
    - SHEAR =  $1.000000E+00 \text{ N}/(\text{mm}^2)$
    - ADHESION\_FACT =  $5.000000E-01$

**Inclusion Parameters**

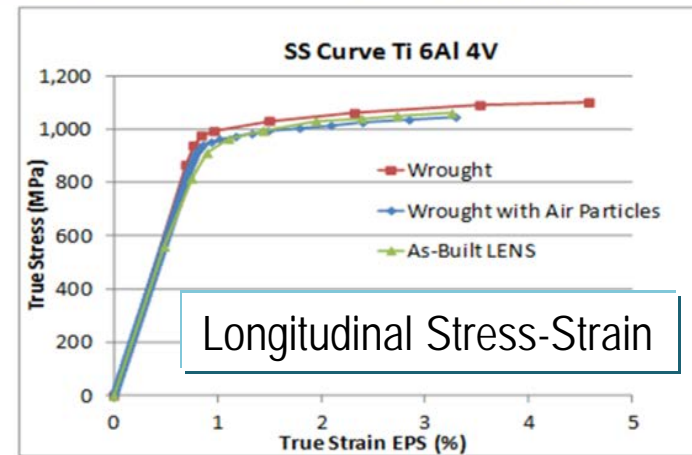
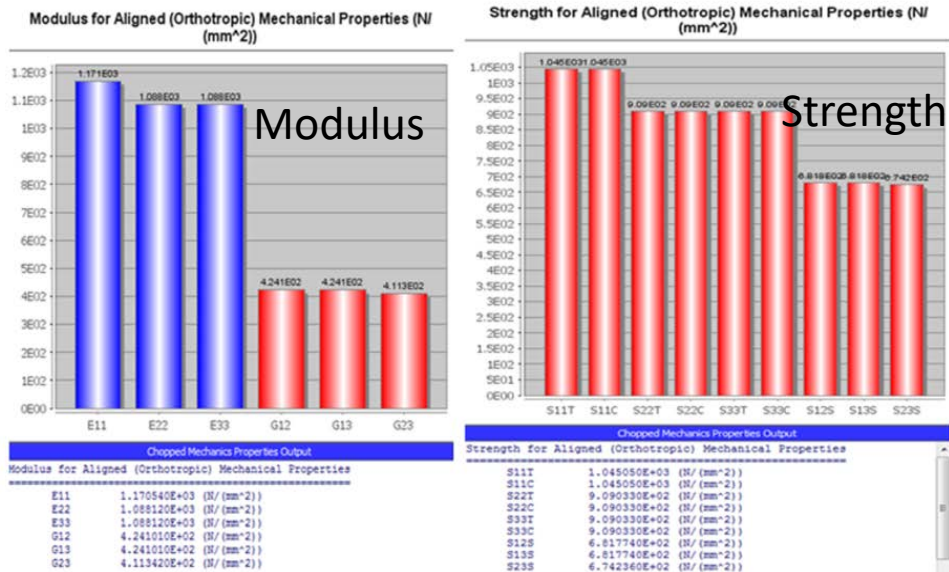
Property	Value
Shape	FIBER
Enable Void As Inclusion	false
Type	STRAIGHT
Void Volume (Fraction)	0.000000E+00
Weight (Fraction)	2.434151E-05
Volume (Fraction)	5.000000E-02
Length (mm)	5.000000E-04
Width (mm)	1.000000E-04
Height (mm)	1.000000E-04
Enable Interphase	No
Dispersion	UNIFORM

**Stress Strain Curve**

Ti-6Al-4V

*Void Volume Fraction 5%*  
*Void : Cylindrical with AR=5*  
*Voids are all aligned in 0 direction*

## Output: Modulus, Strength, Longitudinal Stress-Strain

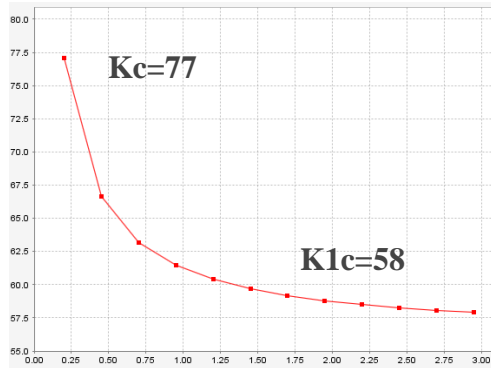




# 3D Printing Fatigue Prediction vs. Test

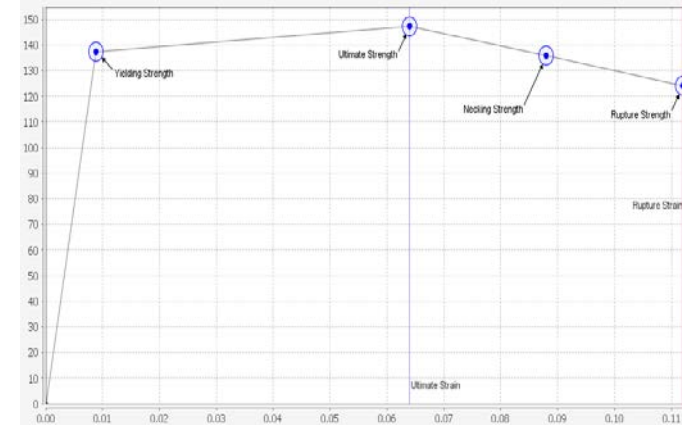
## Validation of Ti 6Al 4V – DMLS at Room Temp

Toughness Vs. Thickness



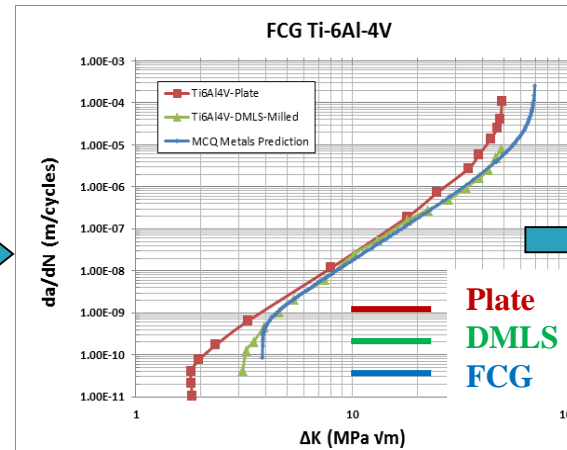
- Material Properties**
  - Yielding Strength = 1.375000E+02 ksi
  - Ultimate Strength = 1.475000E+02 ksi
  - Rupture Strength = 1.240000E+02 ksi
  - Apply Stress = 1.350000E+02 ksi
  - Normal Modulus = 1.550000E+04 ksi
  - Poisson Ratio = 3.300000E-01
  - Ultimate Strain = 6.400000E-02 in/in
  - Rupture Strain = 1.120000E-01 in/in
  - n Constants = 5.570000E-04
  - Alpha Constants = 2.860000E+00
- Geometry**
  - Specimen Thickness = 2.500000E-01 in
  - Gauge Length = 2.000000E+00 in
  - Initial Half Crack Length = 0.000000E+00 in
  - Panel Width = 3.000000E+01 in
  - Panel Thickness = 2.000000E-01 in

Full Stress-Strain Curve

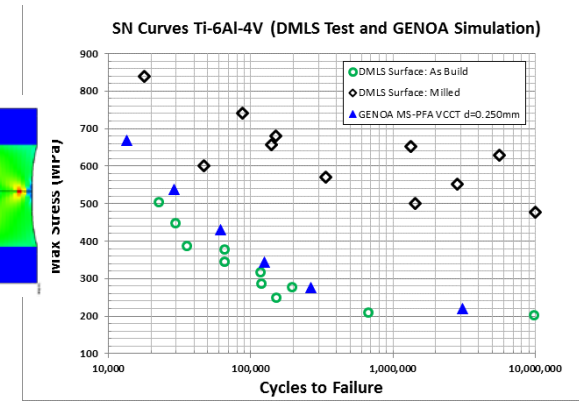


- FCG Materials (1)**
  - Ti-6Al-4V-DMLS**
    - Description: None
    - Material Properties**
      - P Constant = 2.500000E-01
      - Q Constant = 7.500000E-01
      - $Kc = 7.100000E+01 \text{ ksi} \cdot \sqrt{\text{in}}$
      - $K1c = 4.100000E+01 \text{ ksi} \cdot \sqrt{\text{in}}$
      - Stress Ratio = 1.000000E-01
      - Plate Width = 5.000000E+00 in
      - Maximum Stress = 1.500000E+01 ksi
      - Alpha Constant = 2.500000E+00
      - Young's Modulus = 1.690000E+04 ksi
      - Yielding Strength = 1.400000E+02 ksi
      - alpha1 = 1.125000E+00
      - alpha2 = 9.300000E-01
      - beta1 = 1.000000E-07
      - beta2 = 5.000000E-03
      - Kth Ratio = 1.200000E+01
      - Plate Thickness = 9.000000E-01 in

FCG: Output



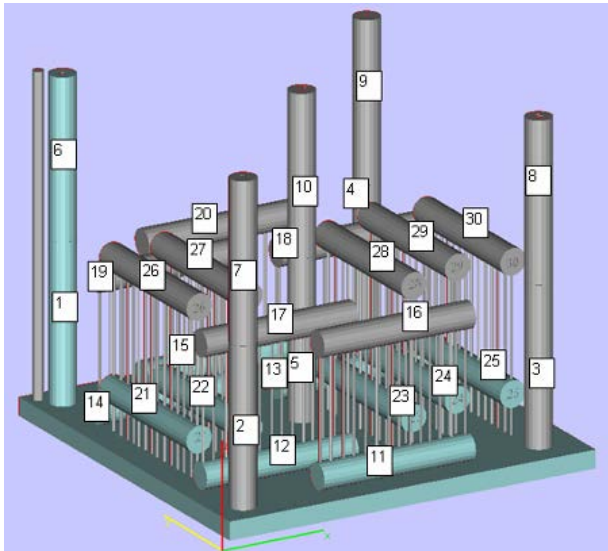
S<sub>N</sub> Prediction/Validation R=0.1



# Allowable Generation: EBM Ti-6Al-4V

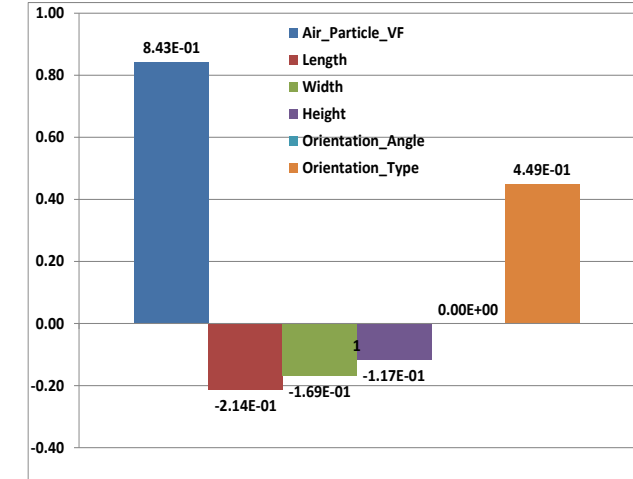


## AM Test Data Scatter Predicted (Yield, Ultimate and Strain) at Room and 700F



- **Print Direction** will affect stiffness and strength properties
- **Void Shapes and Sizes** are key in determining properties
- **Scatter (COV) Prediction** was performed with acceptable results for Room and High Temperature

### Yield Sensitivities for Test Guidance

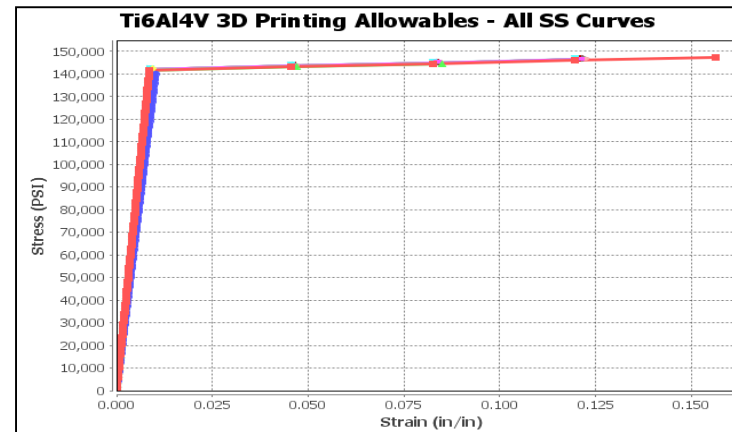


Oxygen Level, % 0.224 %

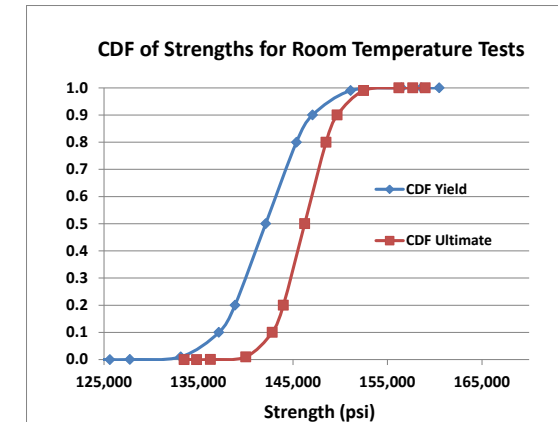
### Prediction Vs. Test at RT Yield, Ultimate, Elongation

RT	YS, ksi	MCQ	%Diff	UTS, Ksi	MCQ	%Diff	El, %	MCQ	%Diff
Mean	141.1	142.1	-0.7	146.1	146.2	-0.1	13.9	12.6	9.4
SD	3.96	3.86	2.4	2.81	2.68	4.5	1.22	1.25	-2.6
COV (%)	2.81	2.72	3.1	1.92	1.83	4.6	8.78	9.76	-11.1
HT	YS, ksi	MCQ	%Diff	UTS, Ksi	MCQ	%Diff	El, %	MCQ	%Diff
Mean	78.1	75.3	3.5	96.0	87.7	8.6	19.1	18.2	4.9
SD	2.83	2.79	1.4	2.46	2.55	-3.8	0.84	0.91	-7.4
COV (%)	3.63	3.71	-2.2	2.56	2.91	-13.6	4.42	4.98	-12.9

### SS Curves from MCQ Predictions



### CDFs for Reliability



# Part Qualification & Requirement

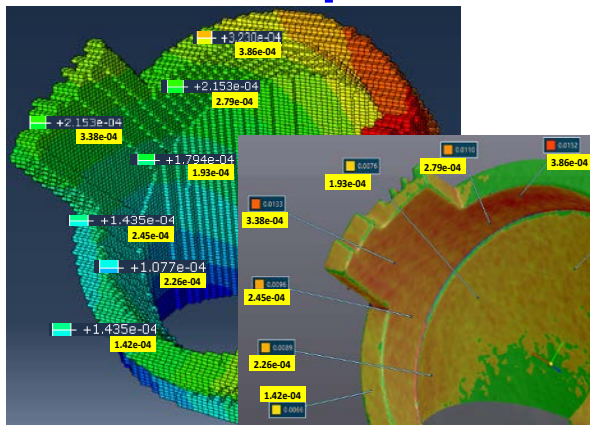
## Qualification Categories

Qualification Category	Description
1-Micro defects	Micro voids/Density during thermal history, super melting sintering and solidification
2-Macro defects	Macro porosity: Printing error around hole and boundary
3-Surface roughness	Diffusional creep, Triaxial stress
4-Intergranular cracks	Diffusional creep, Biaxial stress
5-Scatter in material properties	Stress-strain relation (yield stress, ultimate/plastic strain) due to voids (micro/macro) and cracks
6-Fracture control plan	Characterization of fracture properties, fatigue crack growth, stress intensity curve
7-Warpage	Evaluation of support, Residual stress
8-Net shape	Residual stress, Baseplate removal
9-As-built performance	In-service loading
10-Post heat treatment	Grain growth, lower strain; thermal analysis

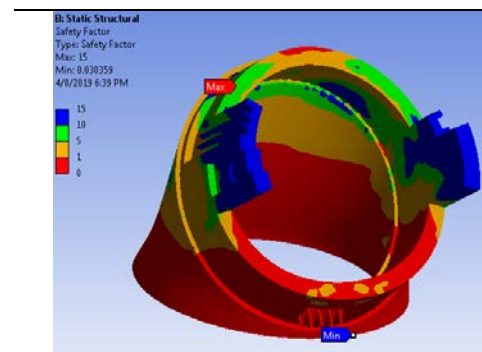
## Primary Machine Parameters

Item	Parameter	Description	Controlled or Predefined
1	Average Power, P	Total Energy Output of Laser	Controlled
2	Scan Velocity, v	Velocity of laser across surface	Controlled
3	Scan Spacing, Ss	Distance between neighboring passes	Controlled
4	Scan Strategy	Pattern of laser scanning (spirals, zig-zag)	Controlled
5	Deposition System Parameters	Recoater vel, pressure, recoater type, closing	Controlled
6	Layer thickness, L	Height of single powder layer	Controlled
7	Powder bed temperature, T <sub>p</sub>	Build temperature of powder bed	Controlled
8	Oxygen level, %O <sub>2</sub>	Likely most important environment parameter	Controlled
9	Gas flow velocity, v <sub>g</sub>	Influences convective cooling	Controlled
10	Ambient Temperature, T <sub>inf</sub>	Affecting cooling, reheat, and residual stress	Controlled

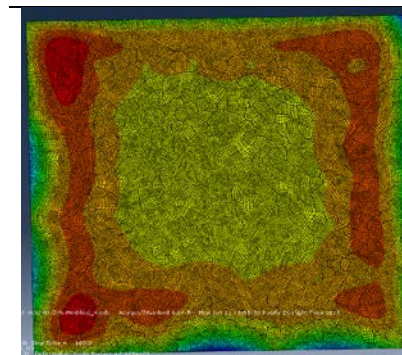
### Netshape



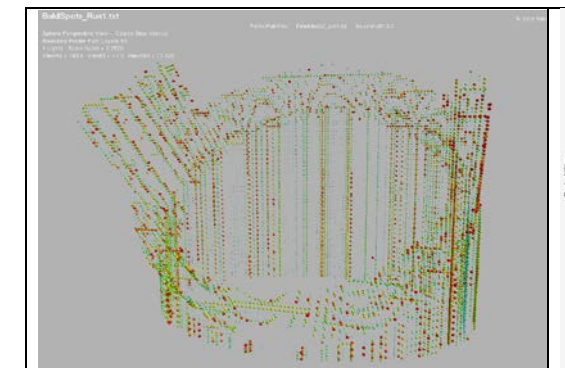
### Safety Margin



### Roughness

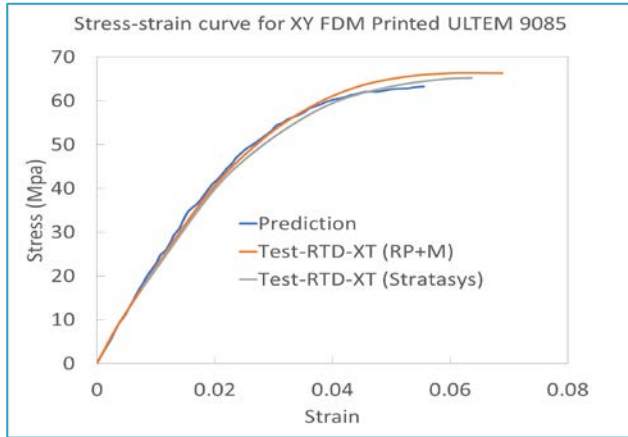


### Porosity

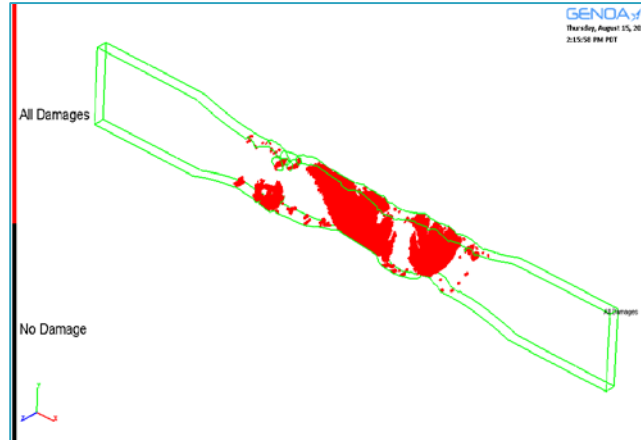


# Part Distortion: ULTEM 9085

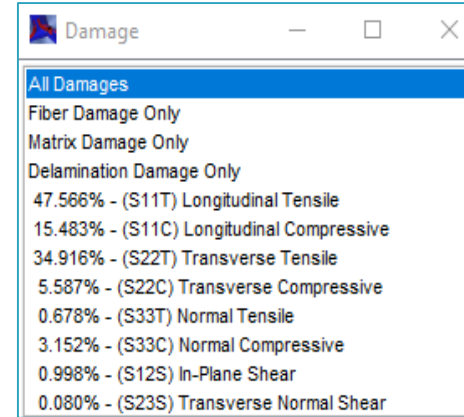
## Stress-Strain Vs test



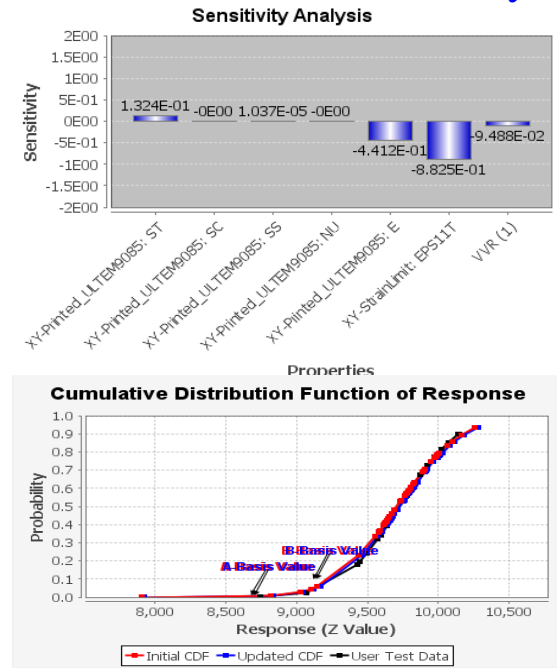
## Damage Location



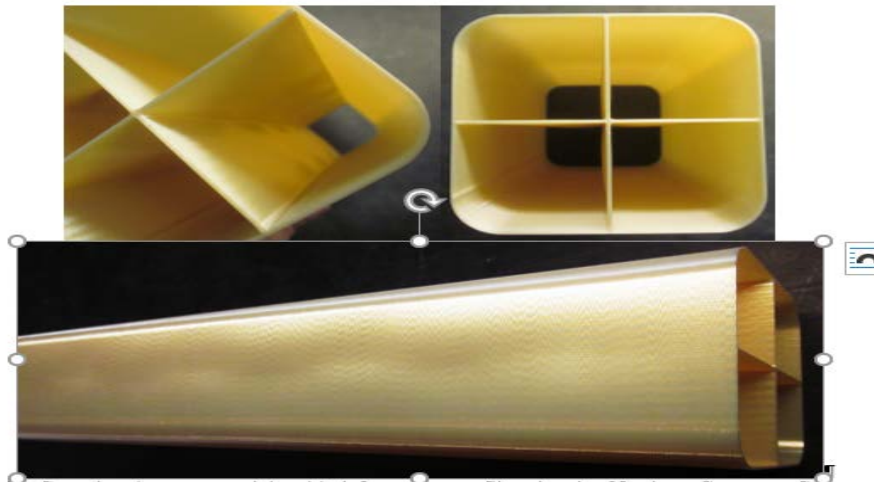
## Damage Index



## Allowable-Sensitivity



Material



## Assumed Print Input Parameters

- Printing Speed: 60mm/s
- Layer Thickness : 0.253mm
- Bead width : 0.33mm
- Chamber or ambient Temperature : 100 °C
- Bottom Plate Temperature : 160 °C
- Bottom Plate Thickness : 1.524 mm
- Bottom Plate Material : Stainless Steel
- Nozzle Temperature : 350 °C

## Input

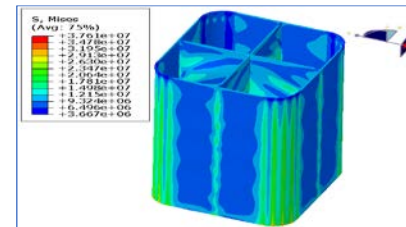
- Temperature dependent Non-linear material properties in ABQUS GENOA UMAT
- External Mesh with 510507 elements and 793560 nodes

## Assumption

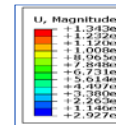
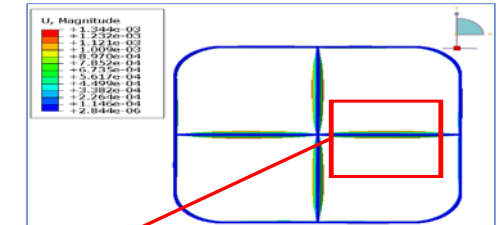
- Layer-by-layer printing
- 1 % spherical shape micro void is implemented which was predicted by TMg

## Results & Conclusion

### Residual Stresses after Bed Removal



### Deformation



### Deformation (Waviness in Print Direction)

Print Direction

Added Value: Prediction of waviness in XY plane and also in Print Direction (Z)

PART

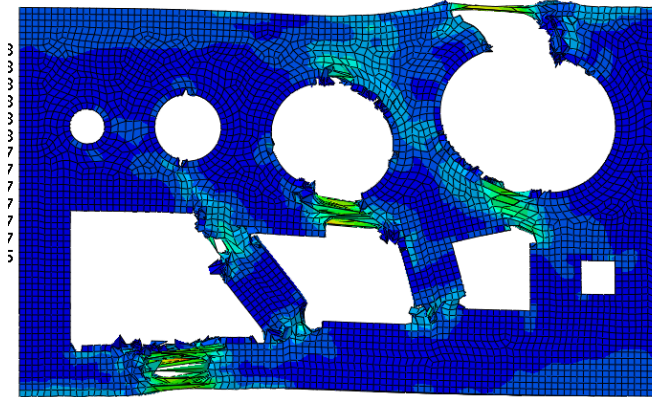
# Service Loading Qualification & Damage Evolution

## Multi-Scale Progressive Failure Analysis

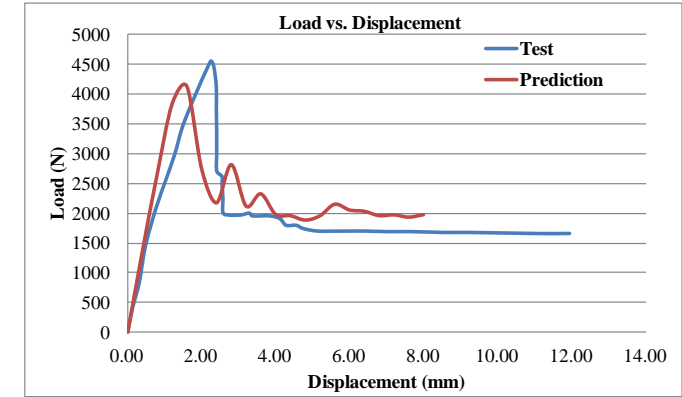
Open-Hole Plate Part – Test



Open-Hole Plate Prediction

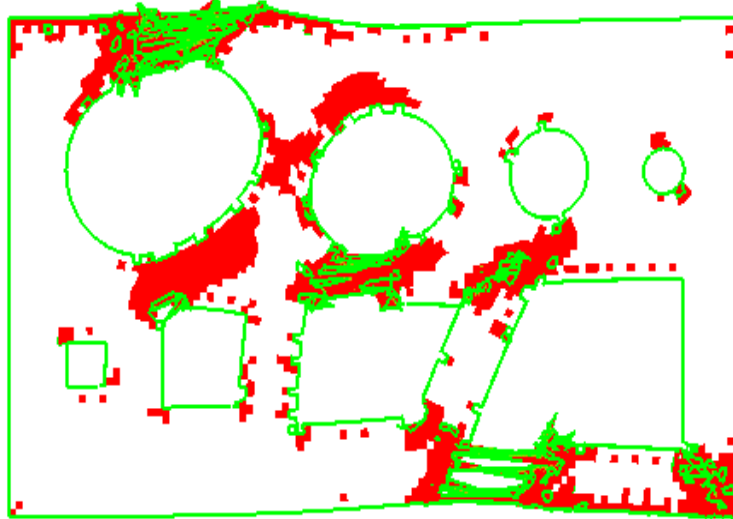


Load Displacement



All Damages

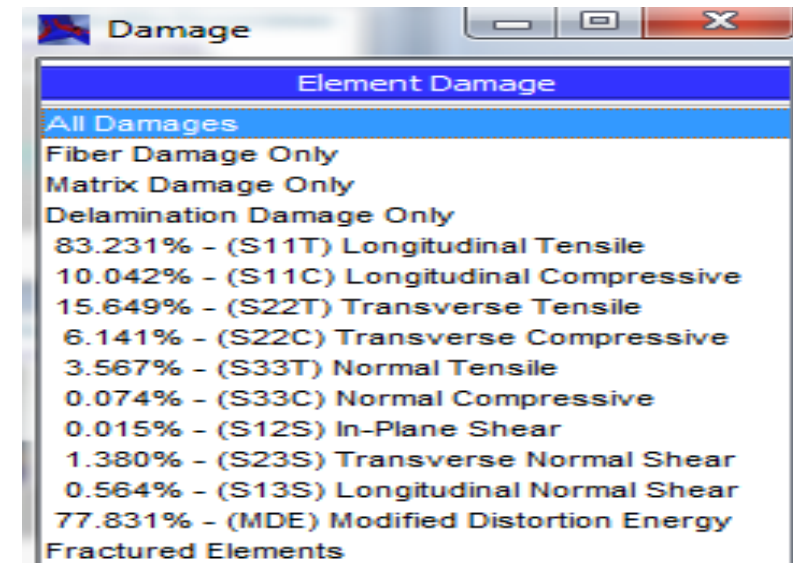
All Damages



No Damage



Damages Type

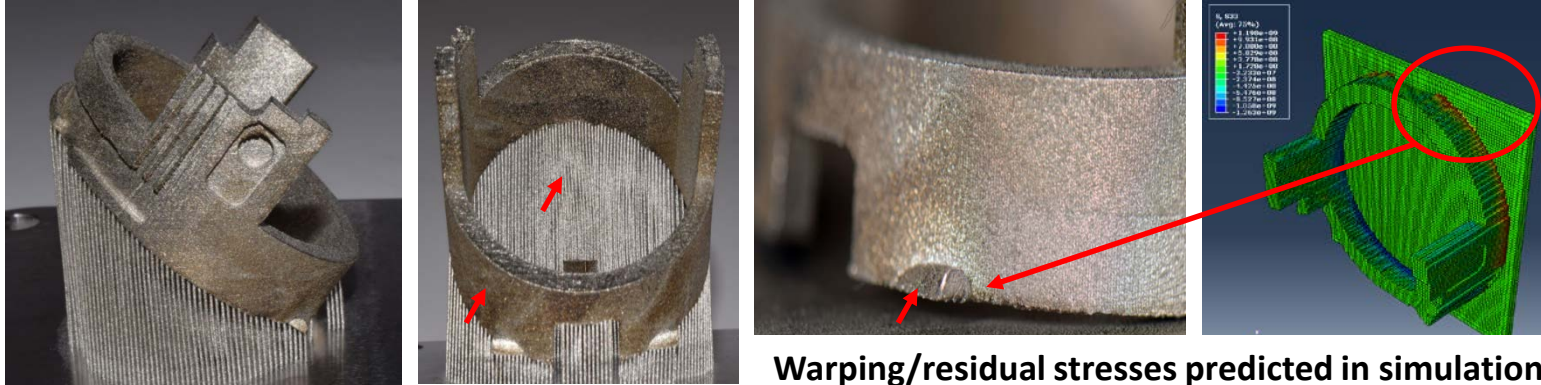


# Case Study: Warpage & Residual Stress Prediction

*Stress buildup leads to Bracket and Support Warpage – Reduce Trial-Error, Scrap Rate Problems*

## Ring Bracket Built Using Inconel 718 Powder

1<sup>st</sup> Build – Bad Part



Warping/residual stresses predicted in simulation

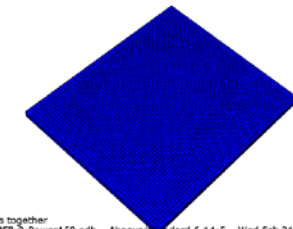
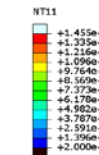
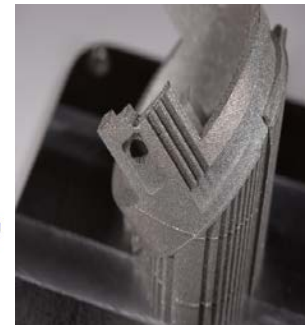
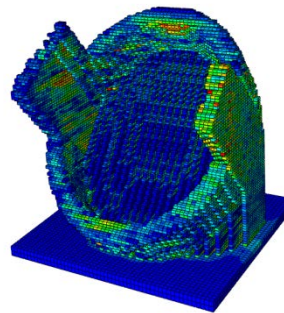
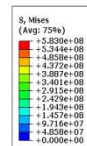
**Warping eliminated through simulation DOE: improved support design and optimized build parameters to reduce residual stresses**

3<sup>rd</sup> Build – Good Part

### Optimized build changes:

1. Mark speed increased
2. Hatch spacing increased
3. Hatch shifted layer to layer (avoids overlap)
4. Support thickness increased

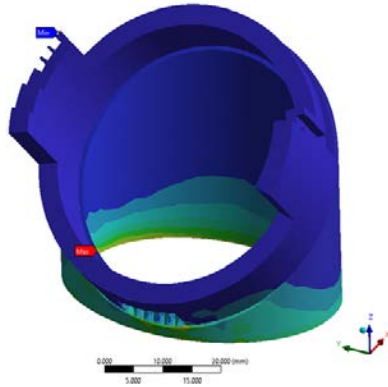
*Lower Residual Stresses* → *Smooth, Warp Free Part*



Combine all layers together  
ODB: model-01-LPFB-2-Power150.odb Abaqus/Standard 6.14-5 Wed Feb 21 08:  
Step: STEP-1-HAZ-REMOVE  
Increment: 0; Step Time = 0.000  
Primary Var: NT11  
Deformed Var: not set; Deformation Scale Factor: not set

# Mount Ring Virtual Quality Assessment

## Net Shape, Defects

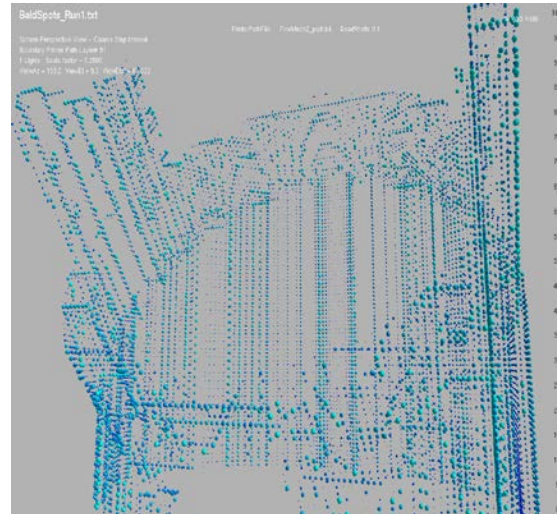
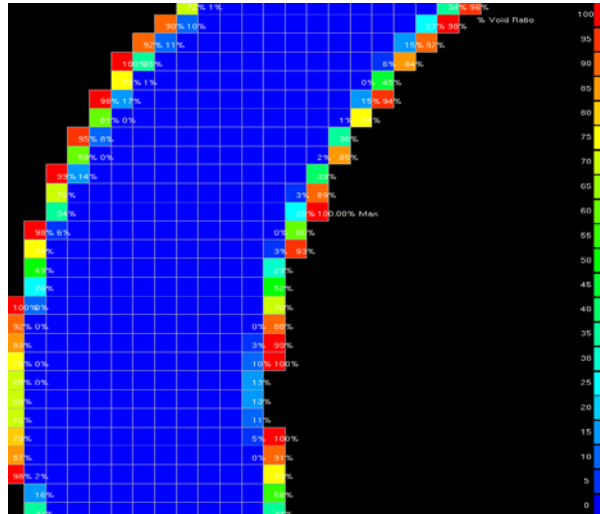


- Detailed stress model for part optimization
- Utilizes mapped void content
  - reduced stiffness and strength
- QUALIFY AS BUILD PARTS

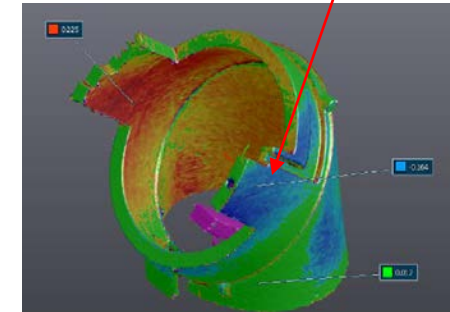
Layer 50 % Voids Content Computed

Voids detected from path coverage amount mapped to detailed stress model

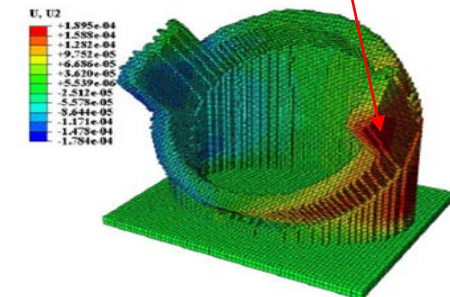
## 2D/3D Defect Computed



Net shape scan (0.0164" in)



Net shape sim (0.0189" in)



Deformation (U<sub>z</sub>)

# Conclusion

## *ICME: Simulated AM Process Considering Defects and Inclusion*

- ❑ **Metal Material Model:**
  - ✓ Effect of Defects,
  - ✓ **Mechanical Properties:** Prediction (Strength-Stiffness) Fracture Properties,
  - ✓ **Fracture Control Plan:** Toughness, Fatigue, Diffusional Creep, Allowables
  - ✓ **Creep Diffusion:** Surface Roughness, Internal Voids and Defects.
  
- ❑ **Process Simulation for Residual Stress and Deflection:**
  - ✓ Void and Defect Prediction and Effect on Mechanical Properties;
  - ✓ **Local Void/Roughness/Oxidation Models,**
  - ✓ **Path Coverage Module:** Detect Voids from Gcode/FEM, Predicts Reduced Properties
  
- ❑ **Qualification Service Model:**
  - ✓ Static, Fatigue, PSD, Impact
  - ✓ Probabilistic Analysis Module: Consider Defects & Uncertainty to Qualify Printed Part
  
- ❑ **In-Situ Monitoring:**
  - ✓ **Visualization & Calculation**
  - ✓ **Data Driven:** Profilometer and IR Thermograph Camera available on AM Printer
  - ✓ **Data Driven Thermal Management:**
    - ✓ Heat Affected Zone, Melt Pool, Material State (Void, Density)
  
- ❑ **Surrogate Model Optimization – Data or Simulation Driven Optimization**
  
- ❑ **Integrated with CAE Standard:**
  - ✓ ANSYS (Work Bench), ABAQUS (CAE Plug-In) , and NX NASTRAN